Features

- Split Gate Trench MOSFET Technology
- Low Thermal Resistance
- Moisture Sensitivity Level 1
- Halogen Free. “Green” Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant(Note2) ("P" Suffix Designates RoHS Compliant. See Ordering Information)

N-Channel MOSFET

Maximum Ratings

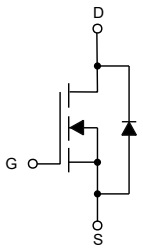
- Operating Junction Temperature Range : -55°C to +175°C
- Storage Temperature Range: -55°C to +175°C
- Thermal Resistance: 40°C/W Junction to Ambient(Note3)
- Thermal Resistance: 0.5°C/W Junction to Case

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Volltage		V_{GS}	±20	V
Continuous Drain Current	T_C=25°C	I_D	246	A
	T_C=100°C		174	
Pulsed Drain Current (Note4)		I_{DM}	984	A
Total Power Dissipation(Note5)		P_D	300	W
Single Pulse Avalanche Energy (Note6)		E_{AS}	1440	mJ

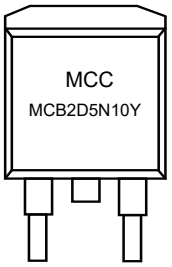
Note:

1. Halogen free "Green” products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. High Temperature Solder Exemption Applied, see EU Directive Annex 7a.
3. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
4. Repetitive rating; pulse width limited by max. junction temperature.
5. P_D is based on max. junction temperature, using junction-case thermal resistance.
6. T_J=25°C, V_{DD}=55V, V_{GS}=10V, R_G=25Ω, L=5mH.

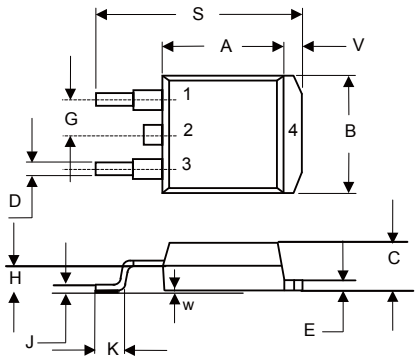
Internal Structure and Marking Code



1. Gate
2,4. Drain
3. Source

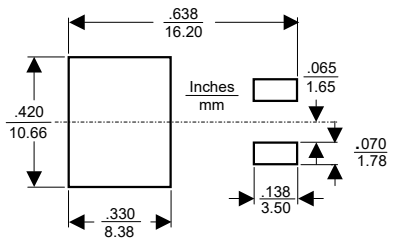


D2-PAK



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.331	0.370	8.40	9.40	
B	0.378	0.417	9.60	10.60	
C	0.165	0.189	4.20	4.80	
D	0.027	0.037	0.68	0.94	
E	0.045	0.055	1.14	1.40	
G	0.1		2.54		TYP.
H	0.096	0.134	2.43	3.40	
J	0.011	0.025	0.28	0.64	
K	0.071	0.131	1.80	3.32	
S	0.575	0.625	14.60	15.87	
V	0.042	0.058	1.07	1.47	
W	0.000	0.010	0.00	0.25	

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=250μA	100			V
Gate-Source Leakage Current	I_{GSS}	V_{DS}=0V, V_{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=100V, V_{GS}=0V			1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	2.0	2.6	4.0	V
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=50A		1.9	2.5	mΩ
		V_{GS}=6V, I_D=20A		2.3	3.1	
Gate Resistance	R_g	f=1 MHz, Open drain		1.3		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				246	A
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=50A			1.2	V
Reverse Recovery Time	t_{rr}	I_F=30A, dI/dt=100A/μs		92		ns
Reverse Recovery Charge	Q_{rr}			167		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	V_{DS}=50V,V_{GS}=0V,f=1MHz		10730		pF
Output Capacitance	C_{oss}			2125		
Reverse Transfer Capacitance	C_{rss}			33		
Total Gate Charge	Q_g	V_{DS}=50V,V_{GS}=10V,I_D=30A		166		nC
Gate-Source Charge	Q_{gs}			34		
Gate-Drain Charge	Q_{gd}			49		
Turn-On Delay Time	$t_{d(on)}$	V_{DD}=50V,V_{GS}=10V, R_G=4.5Ω,I_D=30A		30		ns
Turn-On Rise Time	t_r			65		
Turn-Off Delay Time	$t_{d(off)}$			121		
Turn-Off Fall Time	t_f			107		

Curve Characteristics

Fig.1 - Typical Output Characteristics

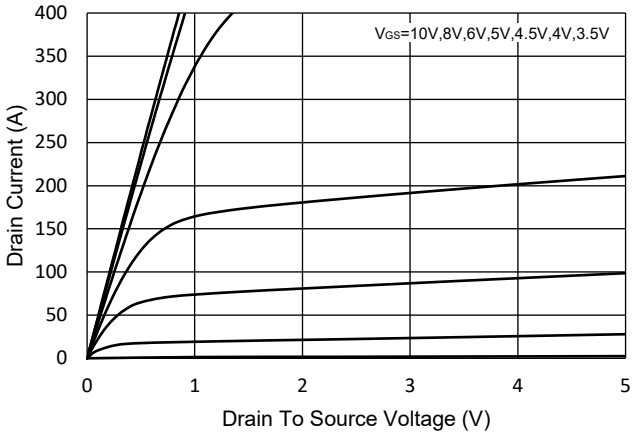


Fig.2 - Transfer Characteristics

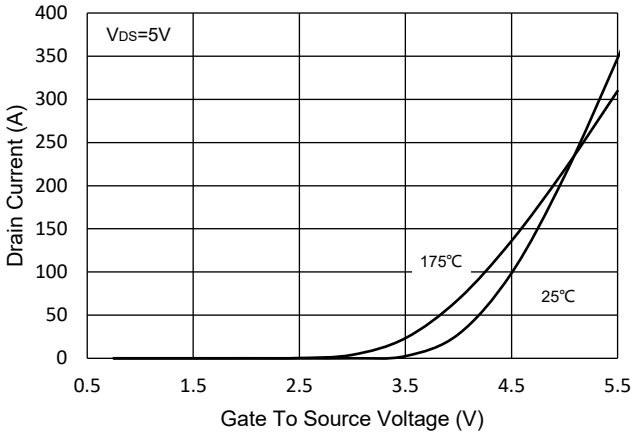


Fig.3 - $R_{DS(ON)}$ - V_{GS}

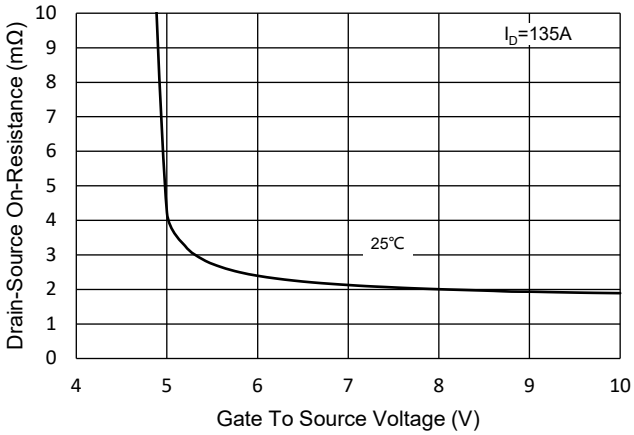


Fig.4 - $R_{DS(ON)}$ - I_D

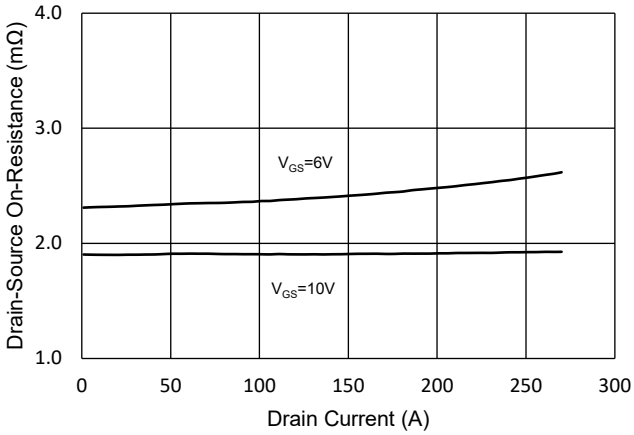


Fig.5 - Capacitance Characteristics

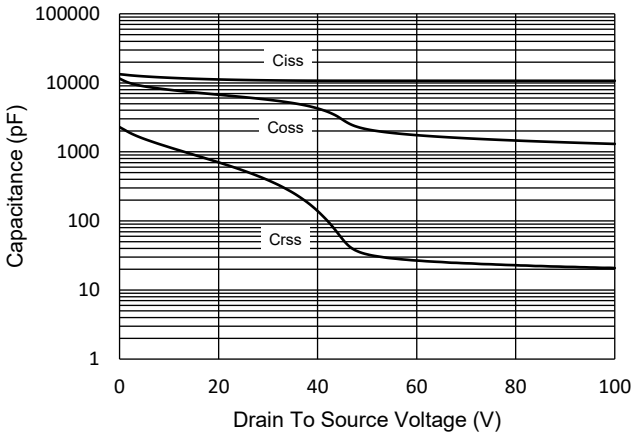
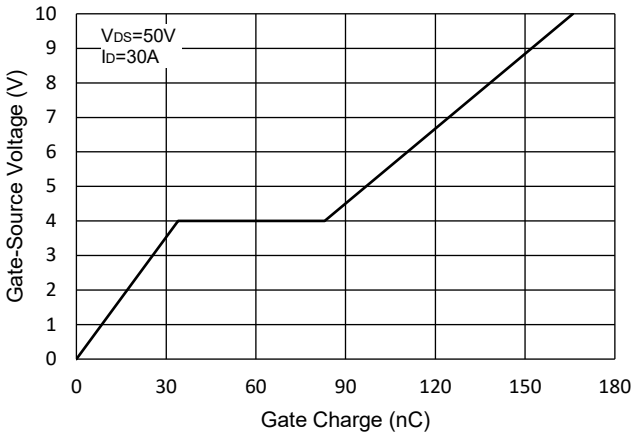


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

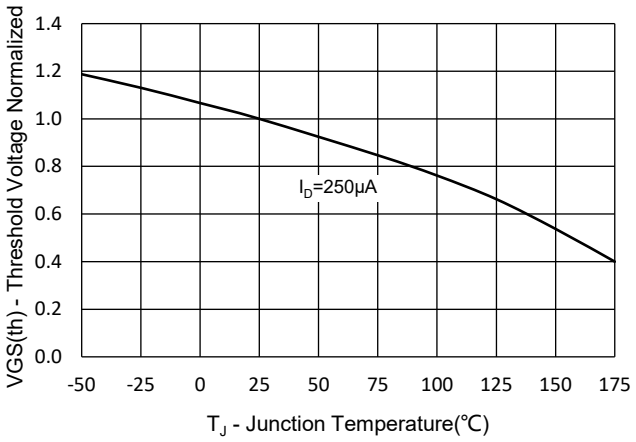


Fig.8 - Normalized On Resistance Characteristics

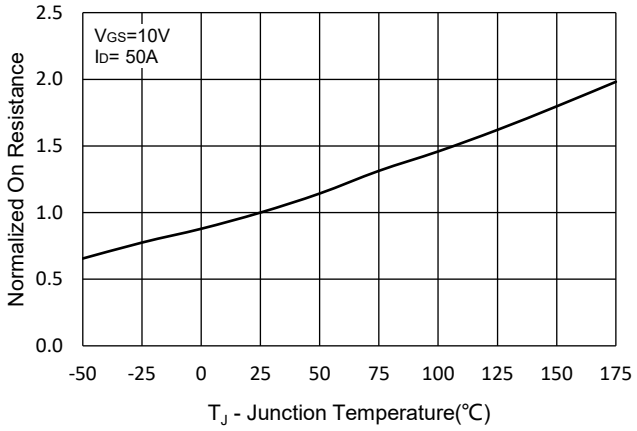


Fig.9 - I_S - V_{SD}

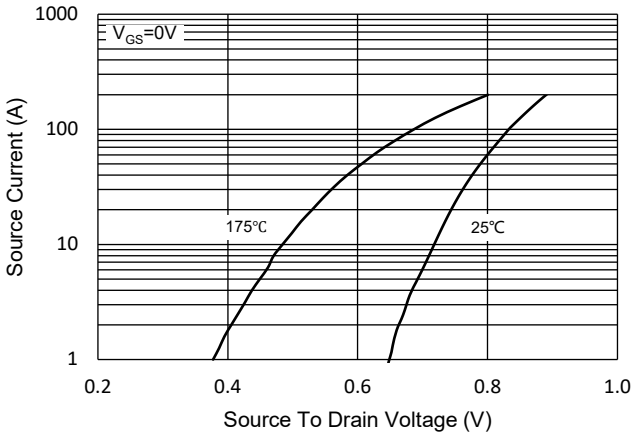


Fig. 10 - Drain Current

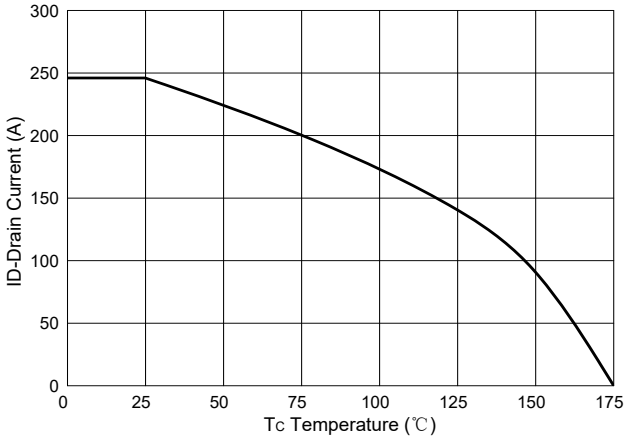
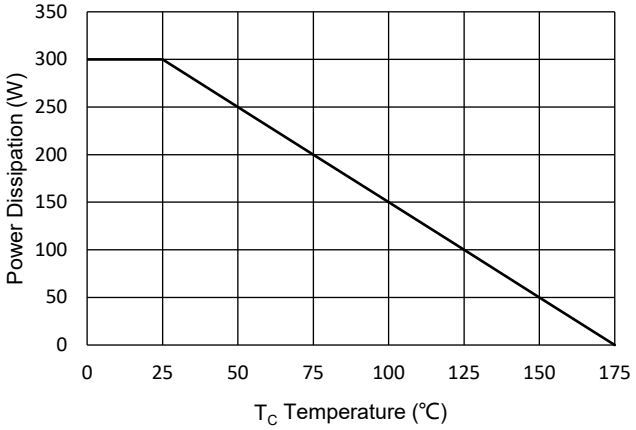


Fig.11 - PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

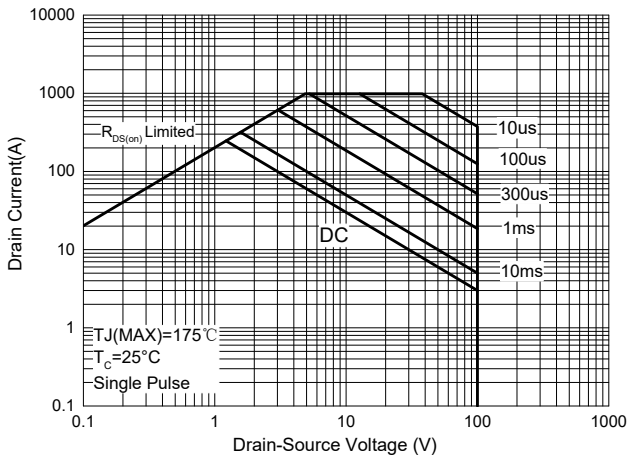
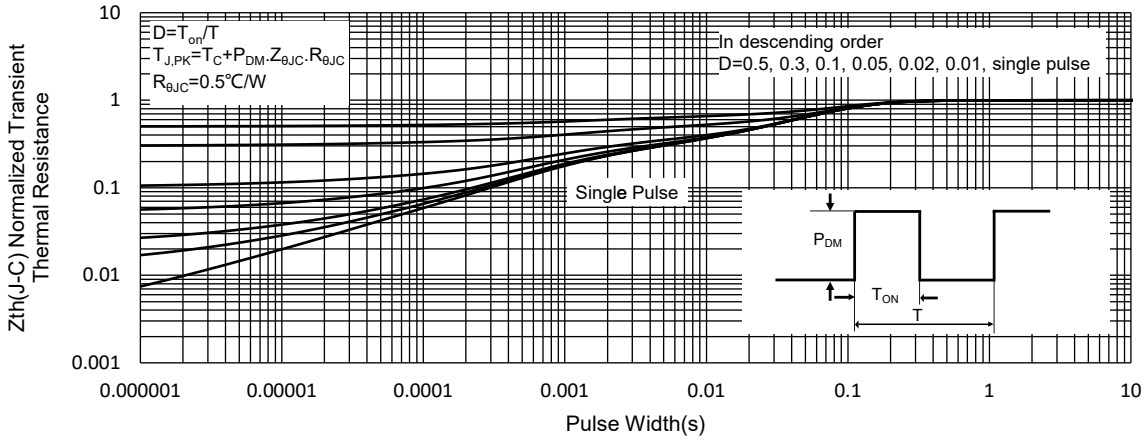


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 800pcs/Reel